

L Number	Hits	Search Text	DB
1	1	("5933048").PN.	USPAT
2	1	("5923048").PN.	USPAT
3	0	("(testadjelements)").PN.	US-PGPUB
4	826	test adj elements	USPAT
5	206	test adj elements	US-PGPUB
6	46	(test adj elements) and semiconductor	US-PGPUB
7	0	((test adj elements) and semiconductor) and (bumps or balls)	USPAT
8	8	((test adj elements) and semiconductor) and (bumps or balls)	US-PGPUB

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L Number	Hits	Search Text	DB
1	0	semiconductor and (test adj elements) and bumps	USPAT
2	5	semiconductor and (test adj elements) and bumps	USPAT
3	1300	semiconductor and test and (solder adj bumps)	USPAT
4	1085	(semiconductor and test and (solder adj bumps)) and pads	USPAT
5	20	(semiconductor and test and (solder adj bumps)) and (first adj2 test) and (second adj test)	USPAT
7	21	(semiconductor and test and (solder adj bumps)) and (first adj2 test wire ) and (second adj test and wire)	USPAT
6	21	(semiconductor and test and (solder adj bumps)) and (first adj2 test signal ) and (second adj test and signal)	USPAT
8	19	(first adj test adj chip) and (second adj test chip)	USPAT
9	1	((first adj test adj chip) and (second adj test chip)) and (bumps or balls)	USPAT
10	130	(test adj chips) and (ball or bumps)	USPAT
11	107	((test adj chips) and (ball or bumps)) and pads	USPAT
12	826	test adj elements	USPAT
13	108	(test adj elements) and chips	USPAT
14	5165	solder adj bumps	USPAT
15	3	((test adj elements) and chips) and solder adj bumps	USPAT
16	10	257/777.ccls. and (test adj chip)	USPAT
17	27	chip and (test adj layer)	USPAT
18	2	(chip and (test adj layer)) and bumps	USPAT

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